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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









### HMC453QS16G / 453QS16GE

v01.0205



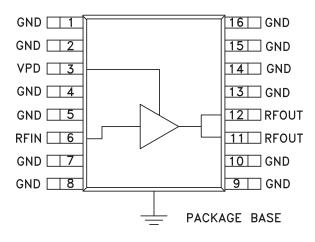
InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

#### **Typical Applications**

The HMC453QS16G / HMC453QS16GE is ideal for applications requiring a high dynamic range amplifier:

- GSM, GPRS & EDGE
- CDMA & W-CDMA
- CATV/Cable Modem
- Fixed Wireless & WLL

#### **Functional Diagram**



#### **Features**

Output IP3: +51 dBm

21.5 dB Gain @ 400 MHz

8 dB Gain @ 2100 MHz

45% PAE @ +32 dBm Pout

+25 dBm CDMA2000 Channel Power@ -45 dBc ACP

Single +5V Supply

Integrated Power Control (VPD)

QSOP16G SMT Package: 29.4 mm<sup>2</sup>

#### **General Description**

The HMC453QS16G & HMC453QS16GE are high dynamic range GaAs InGaP Heterojunction Bipolar Transistor (HBT) 1.6 watt MMIC power amplifiers operating between 0.4 and 2.2 GHz. Packaged in a miniature 16 lead QSOP plastic package, the amplifier gain is typically 21.5 dB at 0.4 GHz and 8 dB at 2.1 GHz. Utilizing a minimum number of external components and a single +5V supply, the amplifier output IP3 can be optimized to +47 dBm at 0.4 GHz or +51 dBm at 2.1 GHz. The power control (VPD) can be used for full power down or RF output power/current control. The high output IP3 and PAE make the HMC453QS16G(E) ideal power amplifiers for Cellular/PCS/3G, WLL, ISM and Fixed Wireless applications.

### Electrical Specifications, $T_A = +25$ °C, Vs = +5V, VPD = +5V [1]

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range		400 - 410	)		450 - 49	6		810 - 96	0	1	710 - 199	90	2	010 - 21	70	MHz
Gain	19	21.5		18	20.5		12	15		6	9		6	8		dB
Gain Variation Over Temperature		0.012	0.02		0.012	0.02		0.012	0.02		0.012	0.02		0.012	0.02	dB/ °C
Input Return Loss		12			15			12			10			15		dB
Output Return Loss		10			10			15			13			18		dB
Output Power for 1dB Compression (P1dB)	29	32		29	32		29	32		28.5	31.5		30	33		dBm
Saturated Output Power (Psat)		32.25			32.25			32.5			32			33.5		dBm
Output Third Order Intercept (IP3) [2]	44	47		47	50		46	49		44	50		48	51		dBm
Noise Figure		7			8.5			7			7.5			6.5		dB
Supply Current (Icq)		725			725			725			725			725		mA
Control Current (IPD)		12			12			12			12			12		mA

<sup>[1]</sup> Specifications and data reflect HMC453QS16G measured using the respective application circuits for each designated frequency band found herein. Contact the HMC Applications Group for assistance in optimizing performance for your application.

[2] Two-tone input power of -10 dBm per tone, 1 MHz spacing.

### HMC453QS16G\* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

### COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

### **EVALUATION KITS**

· HMC453QS16G Evaluation Board.

### **DOCUMENTATION**

#### **Application Notes**

- AN-1363: Meeting Biasing Requirements of Externally Biased RF/Microwave Amplifiers with Active Bias Controllers
- Broadband Biasing of Amplifiers General Application Note
- MMIC Amplifier Biasing Procedure Application Note
- Thermal Management for Surface Mount Components General Application Note

#### **Data Sheet**

· HMC453QS16G Data Sheet

#### TOOLS AND SIMULATIONS .

HMC453OS16G S-Parameters

### REFERENCE MATERIALS 🖳

#### **Quality Documentation**

- HMC Legacy PCN: QS##, QS##E and QS##G,QS##GE packages - Relocation of pre-existing production equipment to new building
- Semiconductor Qualification Test Report: GaAs HBT-B (QTR: 2013-00229)

### DESIGN RESOURCES $\Box$

- HMC453QS16G Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- · Symbols and Footprints

### **DISCUSSIONS**

View all HMC453QS16G EngineerZone Discussions.

### SAMPLE AND BUY 🖳

Visit the product page to see pricing options.

### **TECHNICAL SUPPORT**

Submit a technical question or find your regional support number.

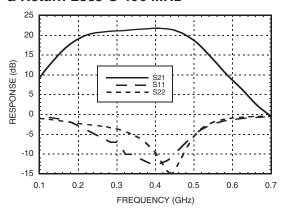
### DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.

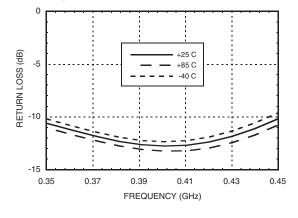




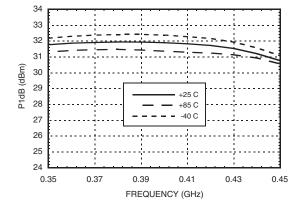
### Broadband Gain & Return Loss @ 400 MHz



### Input Return Loss vs. Temperature @ 400 MHz

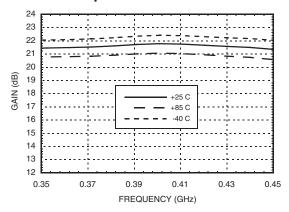


#### P1dB vs. Temperature @ 400 MHz

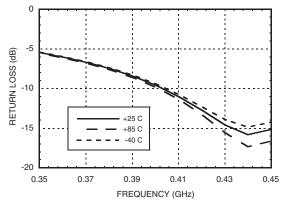


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

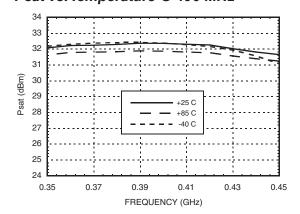
#### Gain vs. Temperature @ 400 MHz



## Output Return Loss vs. Temperature @ 400 MHz



#### Psat vs. Temperature @ 400 MHz

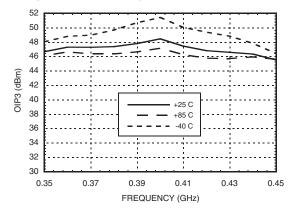




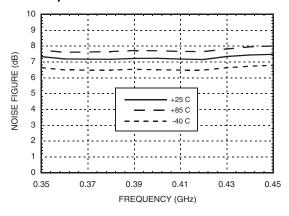


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

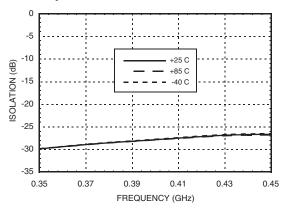
#### Output IP3 vs. Temperature @ 400 MHz



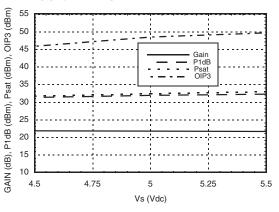
## Noise Figure vs. Temperature @ 400 MHz



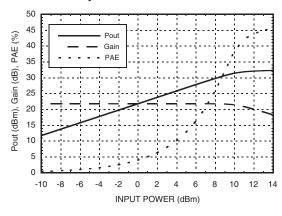
## Reverse Isolation vs. Temperature @ 400 MHz



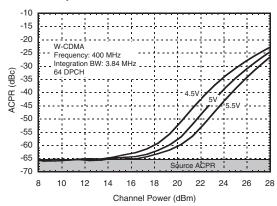
## Gain, Power & IP3 vs. Supply Voltage @ 400 MHz



#### Power Compression @ 400 MHz



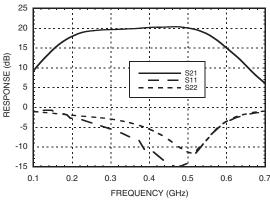
## ACPR vs. Supply Voltage @ 400 MHz W-CDMA, 64 DPCH



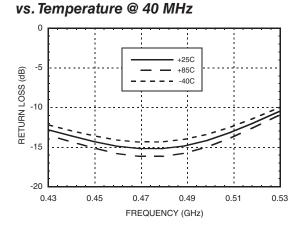




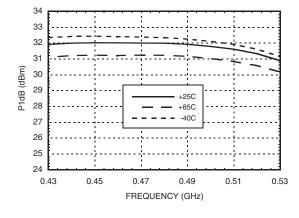
#### **Broadband Gain** & Return Loss @ 470 MHz



**Input Return Loss** 



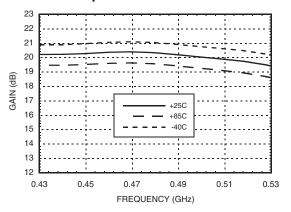
#### P1dB vs. Temperature @ 470 MHz



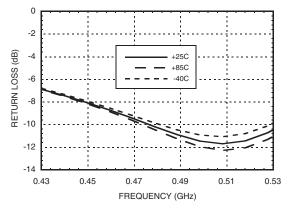
### InGaP HBT 1.6 WATT POWER

# AMPLIFIER, 0.4 - 2.2 GHz

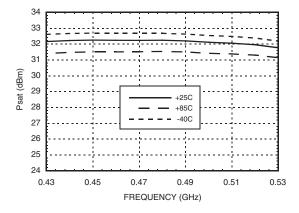
#### Gain vs. Temperature @ 470 MHz



#### **Output Return Loss** vs. Temperature @ 470 MHz



#### Psat vs. Temperature @ 470 MHz

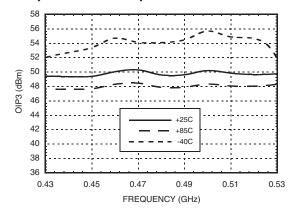




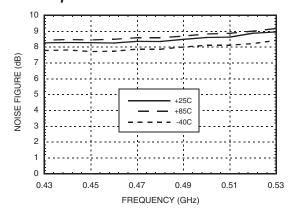


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

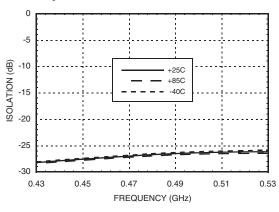
#### Output IP3 vs. Temperature @ 470 MHz



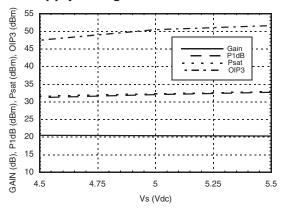
## Noise Figure vs. Temperature @ 470 MHz



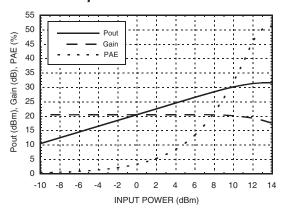
## Reverse Isolation vs. Temperature @ 470 MHz



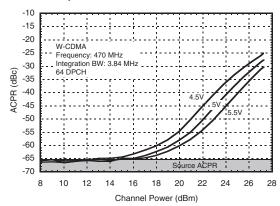
## Gain, Power & IP3 vs. Supply Voltage @ 470 MHz



#### Power Compression @ 470 MHz



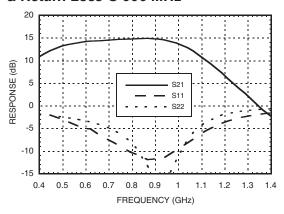
## ACPR vs. Supply Voltage @ 470 MHz W-CDMA, 64 DPCH



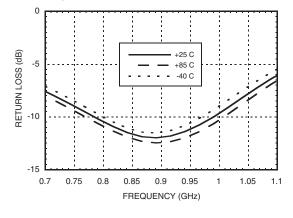




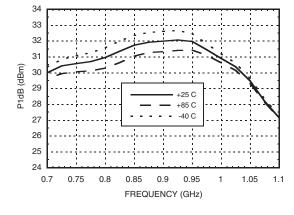
### Broadband Gain & Return Loss @ 900 MHz



## Input Return Loss vs. Temperature @ 900 MHz

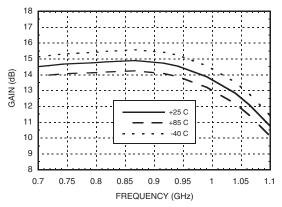


#### P1dB vs. Temperature @ 900 MHz

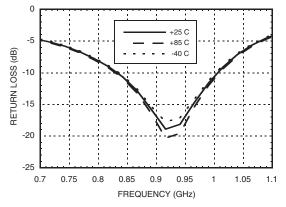


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

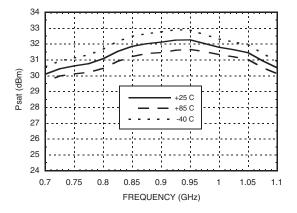
#### Gain vs. Temperature @ 900 MHz



## Output Return Loss vs. Temperature @ 900 MHz



#### Psat vs. Temperature @ 900 MHz

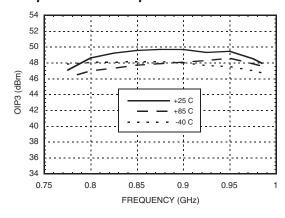




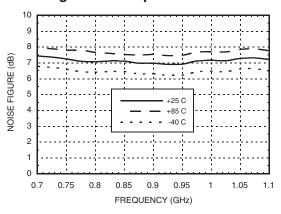


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

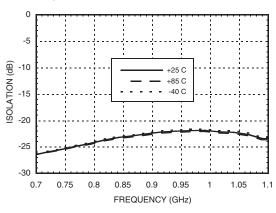
#### Output IP3 vs. Temperature @ 900 MHz



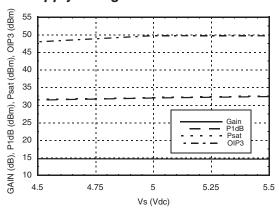
#### Noise Figure vs. Temperature @ 900 MHz



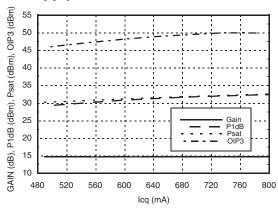
## Reverse Isolation vs. Temperature @ 900 MHz



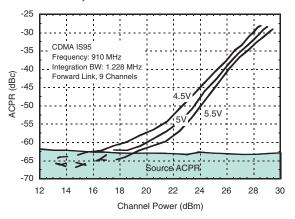
### Gain, Power & IP3 vs. Supply Voltage @ 900 MHz



## Gain, Power & IP3 vs. Supply Current @ 900 MHz\*



# ACPR vs. Supply Voltage @ 910 MHz CDMA IS95, 9 Channels Forward

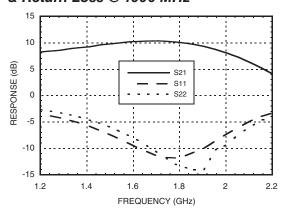


<sup>\*</sup> Icq is controlled by varying VPD.

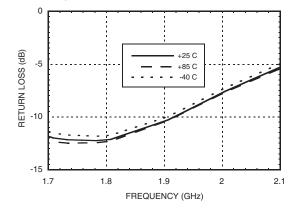




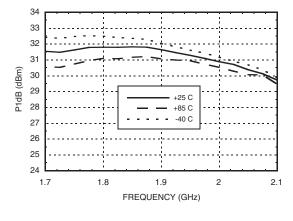
#### **Broadband Gain** & Return Loss @ 1900 MHz



#### **Input Return Loss** vs. Temperature @ 1900 MHz



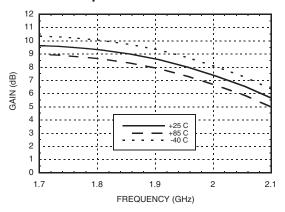
#### P1dB vs. Temperature @ 1900 MHz



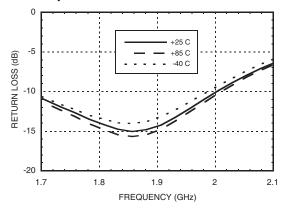
### InGaP HBT 1.6 WATT POWER

# AMPLIFIER, 0.4 - 2.2 GHz

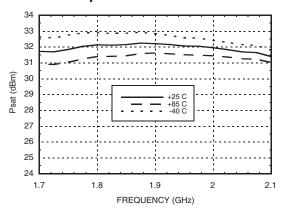
#### Gain vs. Temperature @ 1900 MHz



#### **Output Return Loss** vs. Temperature @ 1900 MHz



#### Psat vs. Temperature @ 1900 MHz

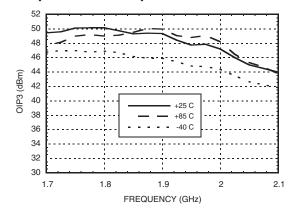




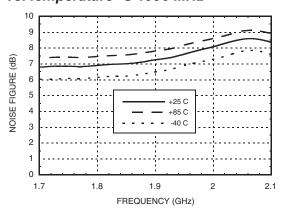


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

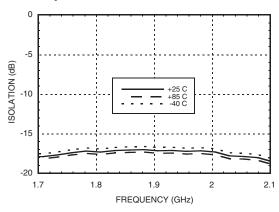
#### Output IP3 vs. Temperature @ 1900 MHz



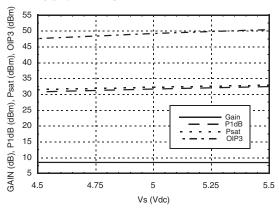
## Noise Figure vs. Temperature @ 1900 MHz



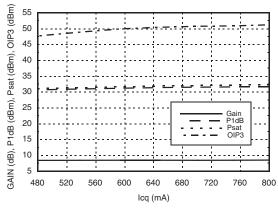
## Reverse Isolation vs. Temperature @ 1900 MHz



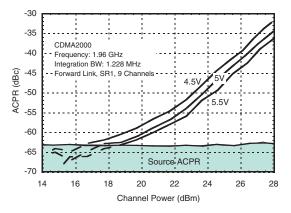
Gain, Power & IP3 vs. Supply Voltage @ 1900 MHz



## Gain, Power & IP3 vs. Supply Current @ 1900 MHz\*



## ACPR vs. Supply Voltage @ 1960 MHz CDMA 2000, 9 Channels Forward



<sup>\*</sup> Icq is controlled by varying VPD.

InGaP HBT 1.6 WATT POWER

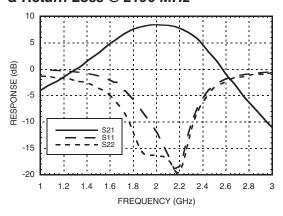
AMPLIFIER, 0.4 - 2.2 GHz



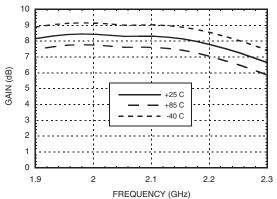
v01.0205



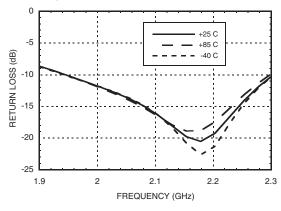
### Broadband Gain & Return Loss @ 2100 MHz



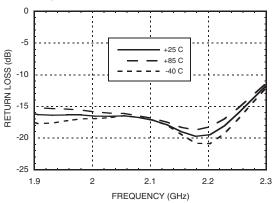
### Gain vs. Temperature @ 2100 MHz



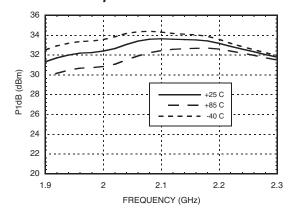
## Input Return Loss vs. Temperature @ 2100 MHz



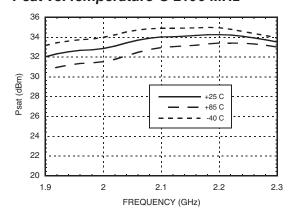
## Output Return Loss vs. Temperature @ 2100 MHz



#### P1dB vs. Temperature @ 2100 MHz



#### Psat vs. Temperature @ 2100 MHz

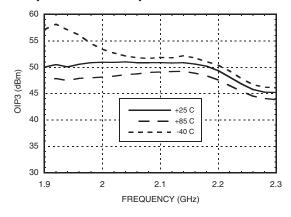




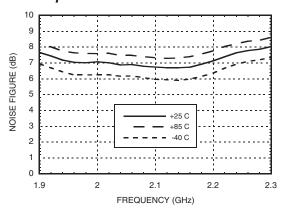


# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

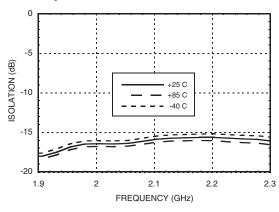
#### Output IP3 vs. Temperature @ 2100 MHz



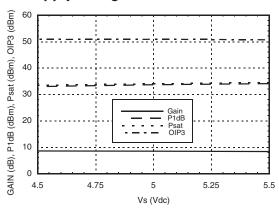
## Noise Figure vs. Temperature @ 2100 MHz



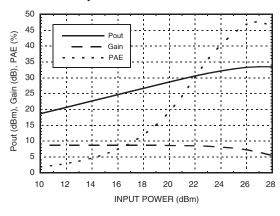
## Reverse Isolation vs. Temperature @ 2100 MHz



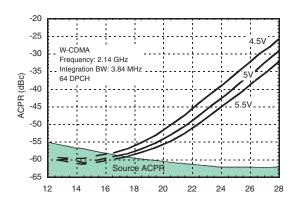
Gain, Power & IP3 vs. Supply Voltage @ 2100 MHz



#### Power Compression @ 2100 MHz



## ACPR vs. Supply Voltage @ 2140 MHz W-CDMA, 64 DPCH



# **ANALOG**DEVICES

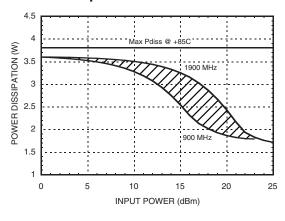
### HMC453QS16G / 453QS16GE

v01.0205



# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

#### **Power Dissipation**



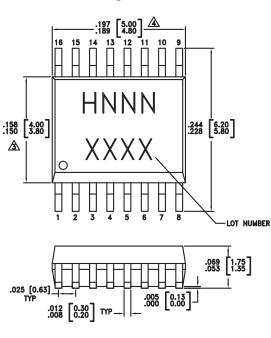
#### **Absolute Maximum Ratings**

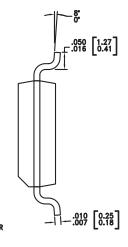
Collector Bias Voltage (Vcc)	+6.0 Vdc
Control Voltage (Vpd)	+5.4 Vdc
RF Input Power (RFIN)(Vs = Vpd = +5Vdc)	+32 dBm
Junction Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 58.5 mW/°C above 85 °C)	3.8 W
Thermal Resistance (junction to ground paddle)	17.1 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

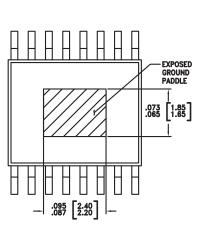


ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

#### **Outline Drawing**







#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- ⚠ DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- A DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC453QS16G	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H453 XXXX
HMC453QS16GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	H453 XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX

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### HMC453QS16G / 453QS16GE

v01.0205



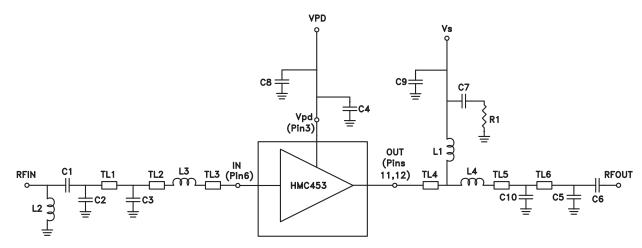
# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

#### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
1, 2, 4, 5, 7-10, 13-16	GND	These pins & package bottom must be connected to RF/DC ground.	= GND
3	VPD	Power control pin. For maximum power, this pin should be connected to 5V. A higher voltage is not recommended. For lower idle current, this voltage can be reduced.	VPD 0 300
6	RFIN	This pin is DC coupled. Off chip matching components are required. See Application Circuit herein.	ORFOUT
11, 12	RFOUT	RF output and DC Bias input for the output amplifier stage. Off chip matching components are required. See Application Circuit herein.	=

#### 400 MHz Application Circuit

This circuit was used to specify the performance for 400-410 MHz operation. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1	TL2	TL3	TL4	TL5	TL6
Impedance	50 Ohm					
Physical Length	0.22"	0.04"	0.04"	0.16"	0.04"	0.05"
Electrical Length	5°	1°	1°	4°	1°	1°
PCB Material: 10 mil Rogers 4350, Er = 3.48						

pF
P pF
pF
) pF
pF
μF
nH
nH
nH
Ohm

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# **ANALOG**DEVICES

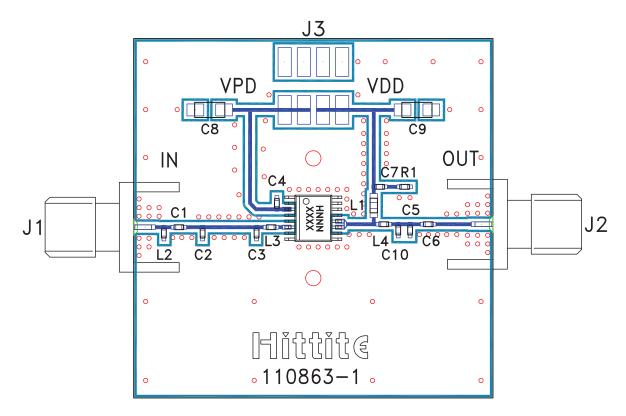
### HMC453QS16G / 453QS16GE

v01.0205



# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.4 - 2.2 GHz

#### 400 MHz Evaluation PCB



#### List of Materials for Evaluation PCB 110865-400 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	2 mm DC Header
C1, C5	12 pF Capacitor, 0402 Pkg.
C2, C10	8.2 pF Capacitor, 0402 Pkg.
C3	6.8 pF Capacitor, 0402 Pkg.
C4, C7	100 pF Capacitor, 0402 Pkg.
C6	39 pF Capacitor, 0402 Pkg.
C8, C9	2.2 µF Capacitor, Tantalum
L1	47 nH Inductor, 0603 Pkg.
L2	40 nH Inductor, 0402 Pkg.
L3, L4	4.3 nH Inductor, 0402 Pkg.
R1	5.1 Ohm Resistor, 0402 Pkg.
U1	HMC453QS16G / HMC453QS16GE Linear Amp
PCB [2]	110863 Evaluation PCB, 10 mils

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of VIA holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

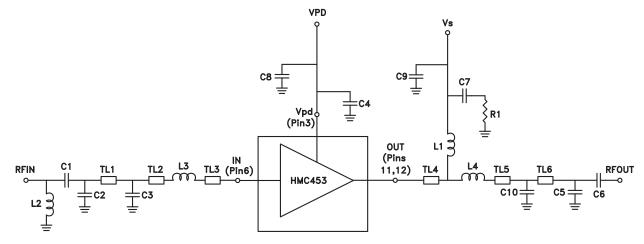




# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 470 MHz Application Circuit

This circuit was used to specify the performance for 450-496 MHz operation. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1	TL2	TL3	TL4	TL5	TL6
Impedance	50 Ohm					
Physical Length	0.22"	0.04"	0.04"	0.16"	0.04"	0.05"
Electrical Length	6°	1°	1°	4°	1°	1°
PCB Material: 10 mil Rogers 4350, Er = 3.48						

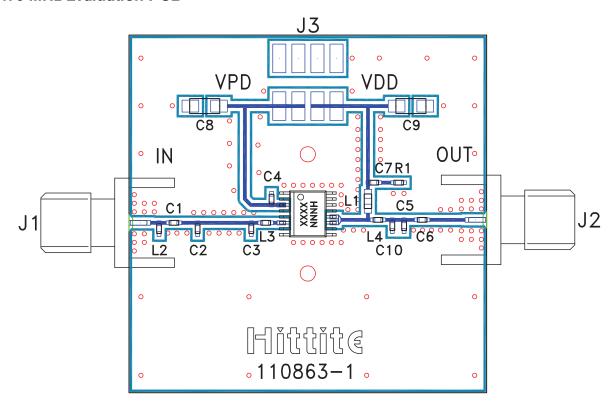
Recommended C	component Values
C1	12 pF
C2	8.2 pF
C3	6.8 pF
C4, C7	100 pF
C5	10 pF
C6	39 pF
C8, C9	2.2 μF
C10	5.6 pF
L1	47 nH
L2	40 nH
L3, L4	4.3 nH
R1	5.1 Ohm





# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 470 MHz Evaluation PCB



#### List of Materials for Evaluation PCB 110976-470 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	2 mm DC Header
C1	12 pF Capacitor, 0402 Pkg.
C2	8.2 pF Capacitor, 0402 Pkg.
C3	6.8 pF Capacitor, 0402 Pkg.
C4, C7	100 pF Capacitor, 0402 Pkg.
C5	10 pF Capacitor, 0402 Pkg.
C6	39 pF Capacitor, 0402 Pkg.
C8, C9	2.2 µF Capacitor, Tantalum
C10	5.6 pF Capacitor, 0402 Pkg.
L1	47 nH Inductor, 0603 Pkg.
L2	40 nH Inductor, 0402 Pkg.
L3, L4	4.3 nH Inductor, 0402 Pkg.
R1	5.1 Ohm Resistor, 0402 Pkg.
U1	HMC453QS16G / HMC453QS16GE Linear Amp
PCB [2]	110863 Evaluation PCB, 10 mils

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB  $\,$ 

<sup>[2]</sup> Circuit Board Material: Rogers 4350, Er = 3.48

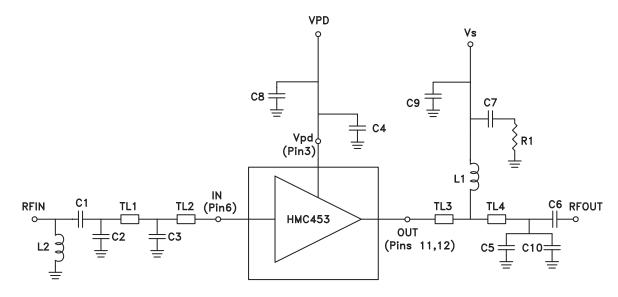




# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 900 MHz Application Circuit

This circuit was used to specify the performance for 810-960 MHz operation. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1	TL2	TL3	TL4	
Impedance	50 Ohm	50 Ohm	50 Ohm	50 Ohm	
Physical Length	0.26"	0.08"	0.12"	0.15"	
Electrical Length 14° 4° 6° 8°				8°	
PCB Material: 10 mil Rogers 4350, Er = 3.48					

omponent Values
5 pF
3.3 pF
100 pF
8.2 pF
56 pF
2.2 μF
1 pF
30 nH
20 nH
5.6 Ohm



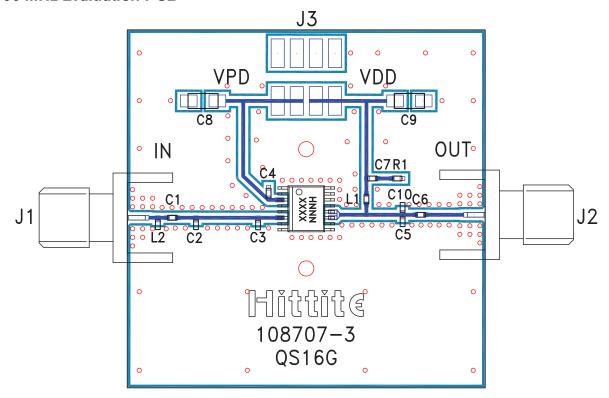
### HMC453QS16G / 453QS16GE

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# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 900 MHz Evaluation PCB



#### List of Materials for Evaluation PCB 108709-900 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	2 mm DC Header
C1	5.0 pF Capacitor, 0402 Pkg.
C2, C3	3.3 pF Capacitor, 0402 Pkg.
C4, C7	100 pF Capacitor, 0402 Pkg.
C5	8.2 pF Capacitor, 0402 Pkg.
C6	56 pF Capacitor, 0402 Pkg.
C8, C9	2.2 µF Capacitor, Tantalum
C10	1.0 pF Capacitor, 0402 Pkg.
L1	30 nH Inductor, 0402 Pkg.
L2	20 nH Inductor, 0402 Pkg.
R1	5.6 Ohm Resistor, 0402 Pkg.
U1	HMC453QS16G / HMC453QS16GE Linear Amp
PCB [2]	108707 Evaluation PCB, 10 mils

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

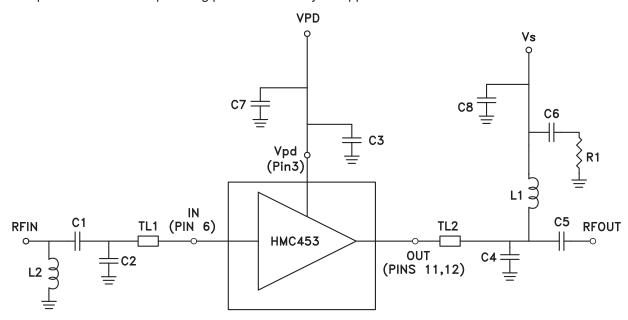




# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 1900 MHz Application Circuit

This circuit was used to specify the performance for 1710-1990 MHz operation. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1	TL2
Impedance	50 Ohm	50 Ohm
Physical Length	0.04"	0.04"
Electrical Length	4°	4°
PCB Material: 10 mil Rogers 4350, Er = 3.48		

Recommended Component Values	
C1	0.8 pF
C2	1.2 pF
C3, C6	100 pF
C4	4.7 pF
C5	15 pF
C7, C8	2.2 μF
L1	18 nH
L2	20 nH
R1	5.6 Ohms



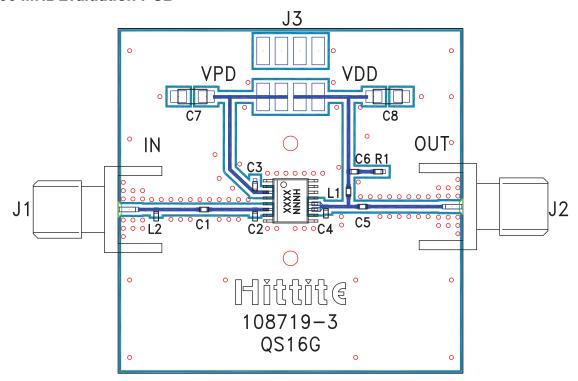
### HMC453QS16G / 453QS16GE

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# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 1900 MHz Evaluation PCB



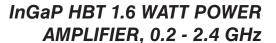
#### List of Materials for Evaluation PCB 108721-1900 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	2 mm DC Header
C1	0.8 pF Capacitor, 0402 Pkg.
C2	1.2 pF Capacitor, 0402 Pkg.
C3, C6	100 pF Capacitor, 0402 Pkg.
C4	4.7 pF Capacitor, 0402 Pkg.
C5	15 pF Capacitor, 0402 Pkg.
C7, C8	2.2 μF Capacitor, Tantalum
L1	18 nH Inductor, 0402 Pkg.
L2	20 nH Inductor, 0402 Pkg.
R1	5.6 Ohm Resistor, 0402 Pkg.
U1	HMC453QS16G / HMC453QS16GE Linear Amp
PCB [2]	108719 Evaluation PCB, 10 mils

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

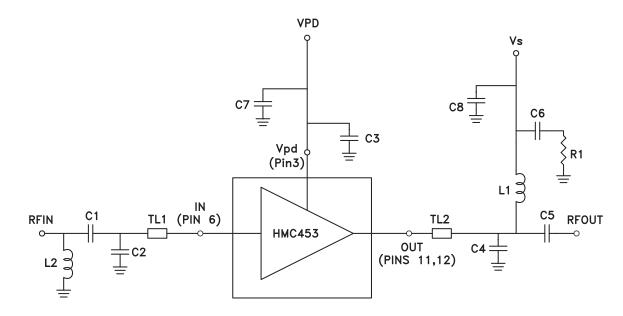
The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.





#### 2100 MHz Application Circuit

This circuit was used to specify the performance for 2100-2170 MHz operation. Contact the HMC Applications Group for assistance in optimizing performance for your application.



	TL1	TL2
Impedance	50 Ohm	50 Ohm
Physical Length	0.04"	0.04"
Electrical Length	5°	5°
PCB Material: 10 mil Rogers 4350, Er = 3.48		

Recommended Component Values	
C1	0.8 pF
C2	1 pF
C3, C6	100 pF
C4	3.9 pF
C5	15 pF
C7, C8	2.2 µF
L1	12 nH
L2	20 nH
R1	5.1 Ohm

# **ANALOG**DEVICES

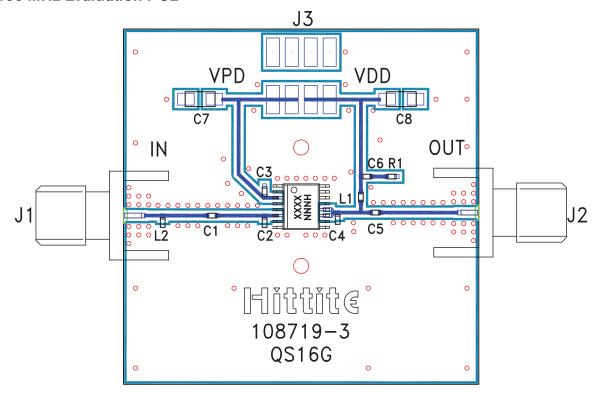
### HMC453QS16G / 453QS16GE

v01.0205



# InGaP HBT 1.6 WATT POWER AMPLIFIER, 0.2 - 2.4 GHz

#### 2100 MHz Evaluation PCB



#### List of Materials for Evaluation PCB 109994-2100 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3	2 mm DC Header
C1	0.8 pF Capacitor, 0402 Pkg.
C2	1.0 pF Capacitor, 0402 Pkg.
C3, C6	100 pF Capacitor, 0402 Pkg.
C4	3.9 pF Capacitor, 0402 Pkg.
C5	15 pF Capacitor, 0402 Pkg.
C7, C8	2.2 µF Capacitor, Tantalum
L1	12 nH Inductor, 0402 Pkg.
L2	20 nH Inductor, 0402 Pkg.
R1	5.1 Ohm Resistor, 0402 Pkg.
U1	HMC453QS16G / HMC453QS16GE Linear Amp
PCB [2]	108719 Evaluation PCB, 10 mils

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350, Er = 3.48

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.